

Thematic Section: Investigation of Physicochemical Processes in Thick-Layer Chemical Copper Coating of Dielectrics. Part 1.

Parameters of working solutions for chemical copper coating

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Abstract

Research of different content stabilizers for selective sedimentation of metals with chemical method on the surface of plates from phenolformaldehyde resins has been carried out and plastic highly adhesive metal-based coatings have been obtained. Solution for chemical copper coating for producing sediments of thickness 25-30 mkm in 4-6 hours in the conditions of permanent maintenance of pH, temperature and periodic adjustment of the solution on basic components has been proposed.